

BS EN 62415:2010



BSI Standards Publication

Semiconductor devices – Constant current electromigration test

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The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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Amendments issued since publication

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 62415

June 2010

ICS 31.080

English version

Semiconductor devices - Constant current electromigration test (IEC 62415:2010)

Dispositifs à semiconducteurs -
Essai d'électromigration en courant
constant
(CEI 62415:2010)

Halbleiterbauelemente -
Konstantstrom-Prüfverfahren
zur Elektromigration
(IEC 62415:2010)

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

The text of document 47/2044/FDIS, future edition 1 of IEC 62415, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62415 on 2010-06-01.

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The following dates were fixed:

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|--|-------|------------|
| – latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement | (dop) | 2011-03-01 |
| – latest date by which the national standards conflicting with the EN have to be withdrawn | (dow) | 2013-06-01 |

Endorsement notice

The text of the International Standard IEC 62415:2010 was approved by CENELEC as a European Standard without any modification.

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